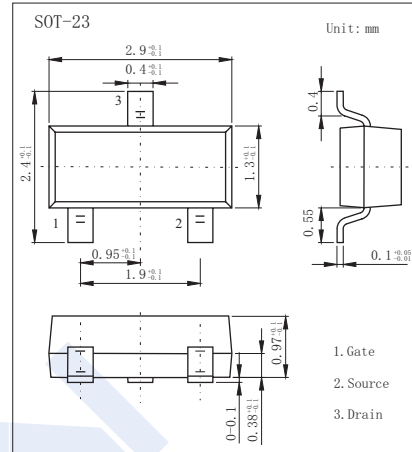
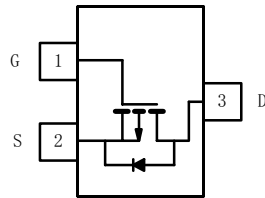


## P-Channel Enhancement MOSFET

### FDN336P

#### ■ Features

- $V_{DS} (V) = -20V$
- $R_{DS(ON)} < 130m\Omega$  ( $V_{GS} = -4.5V$ )
- $R_{DS(ON)} < 190m\Omega$  ( $V_{GS} = -2.5V$ )



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current *1	$I_D$	$T_a = 25^\circ C$	A
		$T_a = 70^\circ C$	
Pulsed Drain Current *2	$I_{DM}$	-10	
Power Dissipation *1	$P_D$	$T_a = 25^\circ C$	W
		$T_a = 70^\circ C$	
Thermal Resistance.Junction- to-Ambient *1	$R_{thJA}$	100	$^\circ C/W$
Thermal Resistance.Junction- to-Ambient *3		166	
Junction Temperature	$T_J$	150	$^\circ C$
Storage Temperature Range	$T_{stg}$	-55 to 150	

\*1 Surface Mounted on FR4 Board,  $t \leq 5$  sec.

\*2 Pulse width limited by maximum junction temperature.

\*3 Surface Mounted on FR4 Board.

## P-Channel Enhancement MOSFET

### FDN336P

#### ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =-250 μ A, V <sub>GS</sub> =0V	-20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DSS</sub> =-20V, V <sub>GS</sub> =0V			-1	μ A
		V <sub>DSS</sub> =-20V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			-10	
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DSS</sub> =0V, V <sub>GS</sub> =±8V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DSS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250 μ A	-0.45		-1	V
Static Drain-Source On-Resistance *1	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.8A		105	130	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2.0A		145	190	
On state drain current *1	I <sub>D(ON)</sub>	V <sub>GS</sub> =-4.5V, V <sub>DSS</sub> ≤ -5V	-6			A
		V <sub>GS</sub> =-2.5V, V <sub>DSS</sub> ≤ -5V	-3			
Forward Transconductance *1	g <sub>FS</sub>	V <sub>DSS</sub> =-5V, I <sub>D</sub> =-2.8A		6.5		S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DSS</sub> =-6V, f=1MHz *2		415		pF
Output Capacitance	C <sub>oss</sub>			223		
Reverse Transfer Capacitance	C <sub>rss</sub>			87		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-4.5V, V <sub>DSS</sub> =-6V, I <sub>D</sub> =-2.8A *2		5.8	10	nC
Gate Source Charge	Q <sub>gs</sub>			0.85		
Gate Drain Charge	Q <sub>gd</sub>			1.7		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>GEN</sub> =-4.5V, V <sub>DSS</sub> =-6V, R <sub>L</sub> =6 Ω, R <sub>G</sub> =6 Ω I <sub>D</sub> =1.0A *3		13	25	ns
Turn-On Rise Time	t <sub>r</sub>			36	60	
Turn-Off DelayTime	t <sub>d(off)</sub>			42	70	
Turn-Off Fall Time	t <sub>f</sub>			34	60	
Continuous Source Current (Diode Conductio	I <sub>S</sub>				-1.6	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.6A, V <sub>GS</sub> =0V		-0.8	-1.2	V

\*1 Pulse test: PW ≤ 300us duty cycle ≤ 2%.

\*2 For DESIGN AID ONLY, not subject to production testing.

\*3 Switching time is essentially independent of operating temperature.

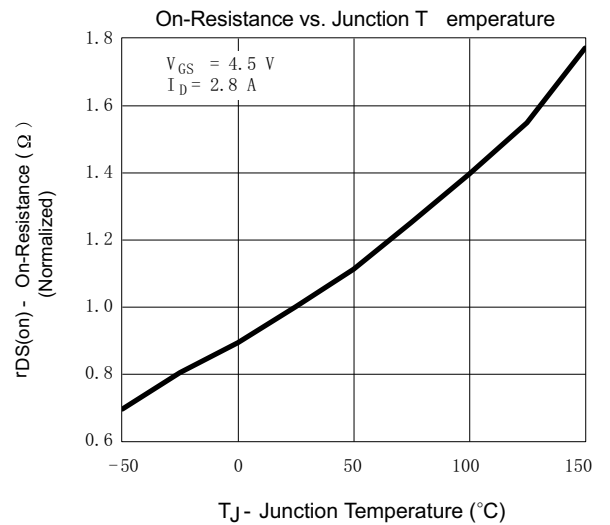
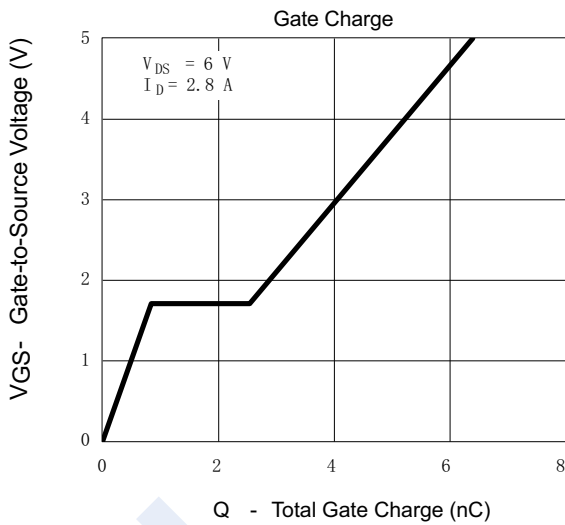
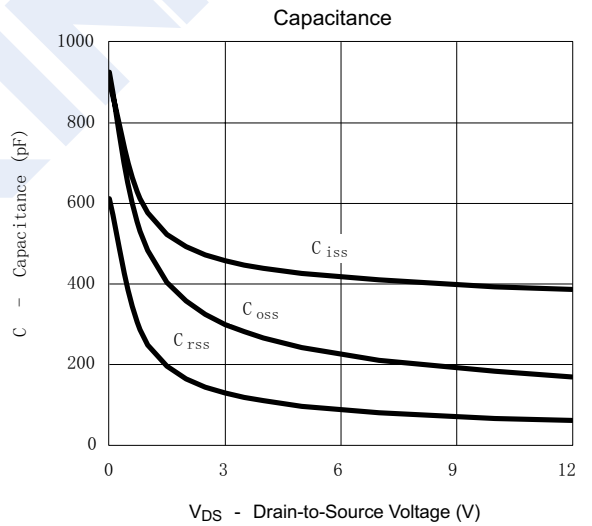
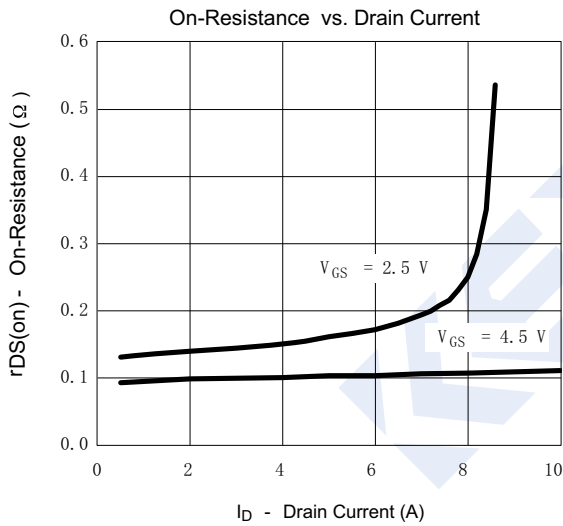
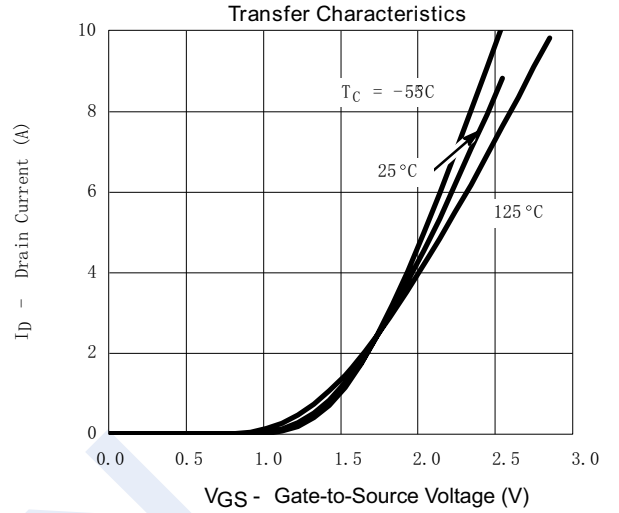
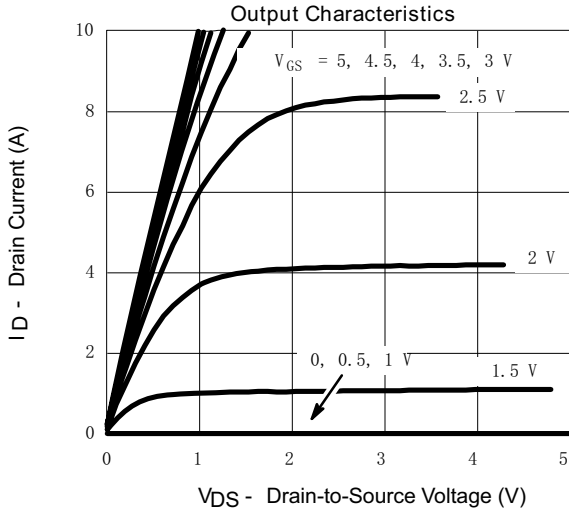
#### ■ Marking

Marking	A1*
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P-Channel Enhancement MOSFET

FDN336P

Typical Characteristics



P-Channel Enhancement MOSFET

FDN336P

Typical Characteristics

